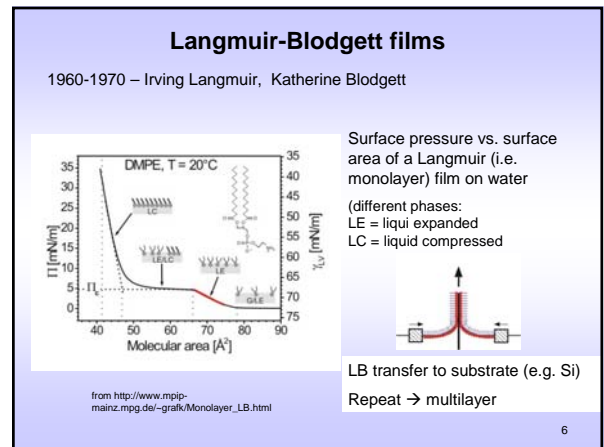


Some limitations to scaling down

- diffraction effects in lithography
- decreasing thickness of insulating layer
 - gate oxide typically 100 nm thick
 - with 5 V – el. field 5×10^8 V/m – tolerable
 - for 20-30 nm $\rightarrow 2 \times 10^9$ V/m – danger of electric **breakdown**
- Inhomogeneity - dopant in low concentration
 - p-type Silicon – typically 10^{22} B-atoms/m³
 - surface conc. = 500 B / μm^2
 - MOSFET channel $1 \times 1 \mu\text{m}^2$ – 500 B under gate
 - if channel reduced to $0.1 \times 0.1 \mu\text{m}^2$ – only 5 B on average could be 3, or 8 \rightarrow **unreliable**
- problems with **heat dissipation**
- **thermal fluctuations**
- also **quantum** effects

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Lithographic methods

- Classical manufacture of integrated circuits
 - shine visible light through mask onto radiation-sensitive "photoresist"
 - positive: where exposed → soluble (polymer degrades)
 - e.g. PMMA (poly(methyl methacrylate))
 - negative: where exposed → insoluble (monomer polymerizes)
 - e.g. novolac (phenol formaldehyde) resin
 - But resolution limited to wavelength of light (ca. 0.5 μm) by diffraction effects
 - use shorter wavelengths

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Electromagnetic spectrum

The diagram shows the electromagnetic spectrum with frequency (ν) in Hz on the top axis and wavelength (λ) in meters on the bottom axis. The spectrum is divided into regions: Radio (10¹-10⁸ Hz), Microwave (10⁸-10¹⁰ Hz), Infrared (10¹⁰-10¹⁴ Hz), Visible (10¹⁴-10¹⁵ Hz), Ultraviolet (10¹⁵-10¹⁶ Hz), X-ray (10¹⁶-10¹⁸ Hz), and Gamma rays (10¹⁸-10²⁰ Hz). A visible spectrum color bar is shown below the visible region, with wavelengths from 700 nm (red) to 400 nm (violet).

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UV lithography

Wavelengths (nm)	Optics
350 - 250	fused silica, quartz
250 - 150	CaF ₂ (hygroscopic – becomes cloudy)

< 100 nm

- no window transmits UV
- even air absorbs it
- Vacuum UV (VUV) - impractical

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X-ray lithography

- for λ around 10 nm – known as:
 - Extreme UV (EUV), or Soft X-rays
 - produced by Xe plasma
 - no transmitting material
 - no focusing optics based on refraction (lenses)
 - focusing by diffraction on artificial multilayers
- harder X-rays – produced by small synchrotrons
 - same focusing problems
 - source expensive
 - but great advantage: large depth of focus
 - high pillars in photoresist can be made, sharp steep walls

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X-ray lithography

- However, since in industrial process mask cannot be held closer than 5 – 40 μm
- resolution limited to 70 – 200 nm (even though λ around 10 nm)

photoresist patterned by X-ray lithography

(from R. Waser (ed.), Nanoelectronics and Information Technology)

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Two types of X-ray producing synchrotrons

A scientific research synchrotron with a 2 GeV electron storage ring (Diamond Light Source, UK)

A compact synchrotron for X-ray lithography with two superconducting 180° bending magnets (Jefferson Labs, USA)

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Ion beam lithography

- e.g. ions of liquid metals (e.g. gallium)
- focused ion beam – can write metal nanowires directly (no need for masks and photoresists)
- can be used to write and repair masks
- e.g. 150 keV H-ions → resolution 0.1 μm
- advantage over electrons:
 - ions are scattered less
 - electrons cannot write directly

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Electron beam lithography

- used in a number of research labs
- used commercially for making masks
- wavelength typically 10 μm (= 0.01 nm = 0.1 \AA)
- resolution down to 5 nm
- can be focused using electrostatic lenses (electron microscope technology)
- beam travel programmable
- not practical for production – too slow

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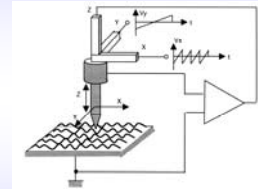
Other lithographies

- Nanoimprint lithography (using rubber stamp)
- also other "top-down" methods
 - will be discussed later

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Scanning Tunnelling Microscopy (STM)

- invented in early 1980s
- conducting nano-probe hovers over surface of a molecularly thin sample on a conducting substrate
- probe feels proximity to atomic orbitals by measuring tunneling current – strongly depends on distance
- → signal in feedback loop with piezoelectric elements driving the cantilever with the probe
- systems tries to keep constant distance from surface
- → output = surface topography
- atomic resolution

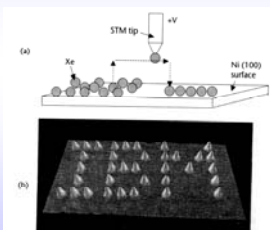


from: A. Nabok, "Organic and Inorganic Nanostructures", Artech House, Boston 2005

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STM

- moving Xe atoms on Ni surface
ultimate top-down technique, but highly impracticable



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